
CF3™ for the world

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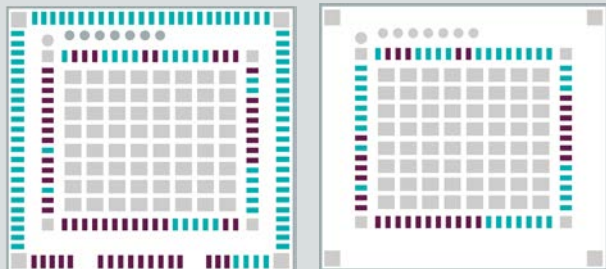
CF3™, Common Flexible Form Factor

CF3 Standard

CORE PINS never change

EXTENSION PINS additional features

CUSTOM PINS
unique module-specific features



4G

3G

2G

For cellular modules



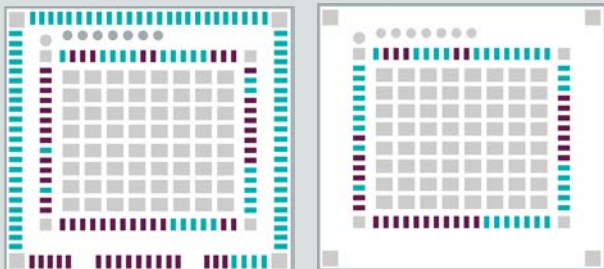
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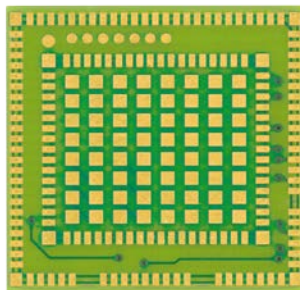
CUSTOM PINS
unique module-specific features



For non-cellular modules



CF3™, Proof of Concept





CF3™, Proof of Concept

flex™

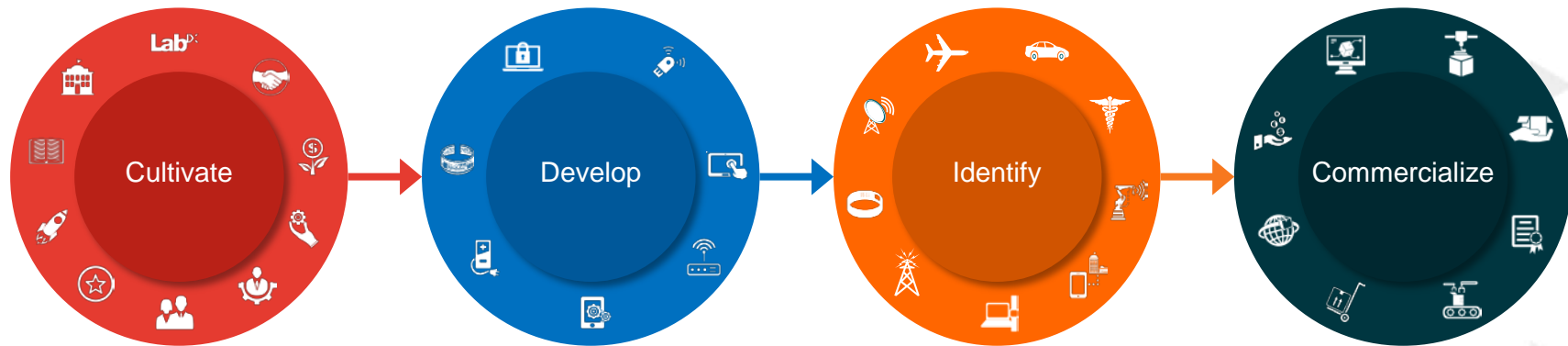



SIERRA
WIRELESS™

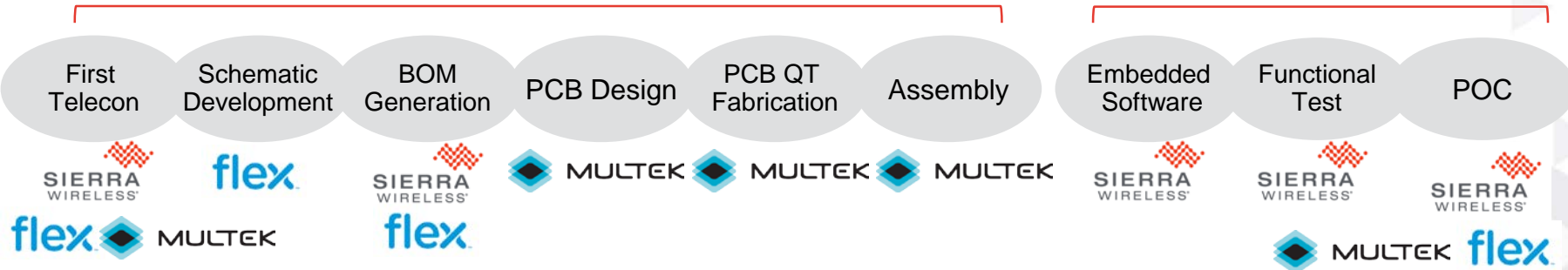


MULTEK

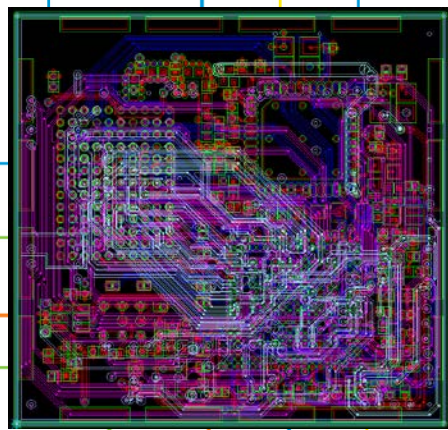
flex - sketch-to-scale™



~ 7 weeks



Advanced HDI PCB Technology for IoT



Every Layer
Interconnect
(ELIC)

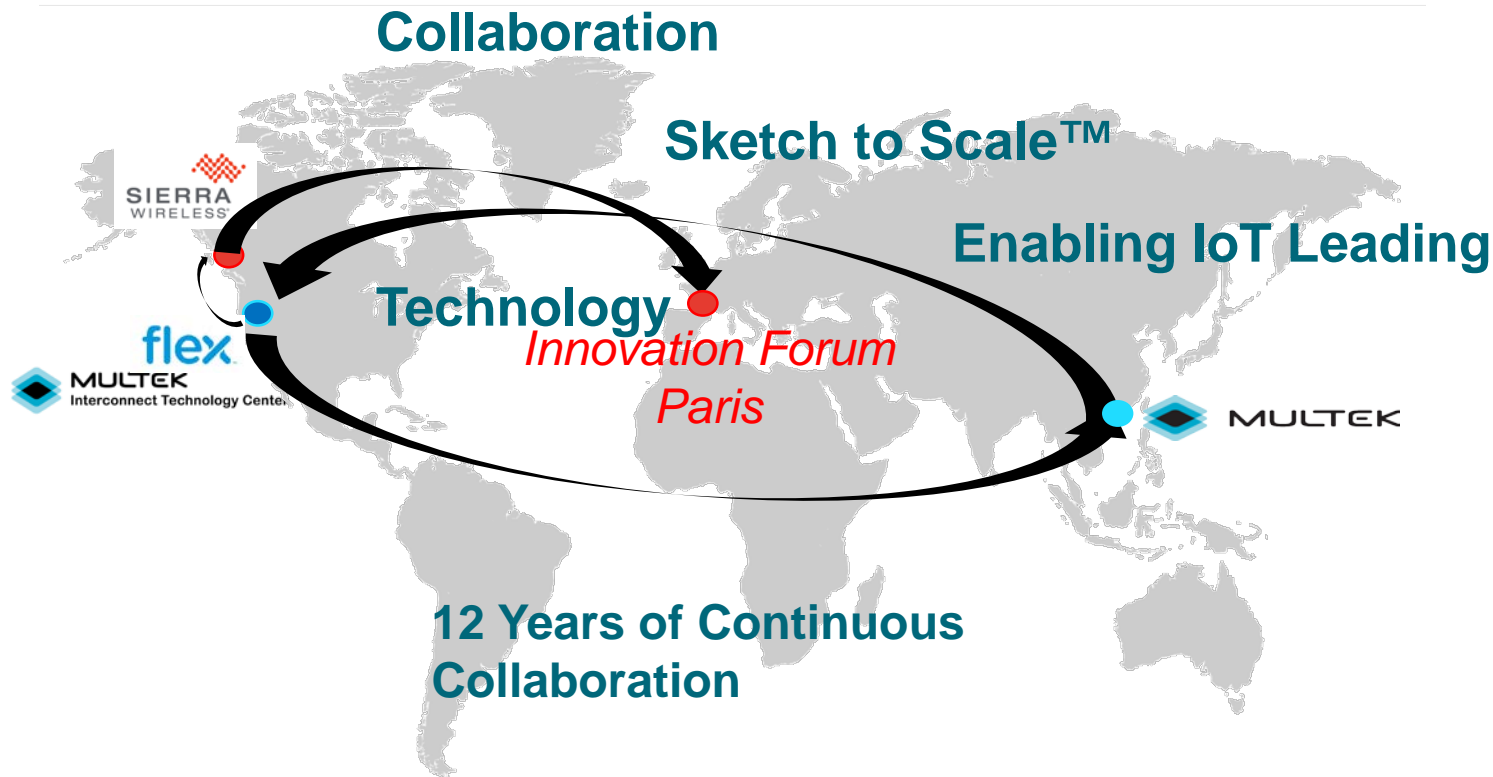
Leveraging
Technology

Board Thickness Specified:	34.70	mil	Over Copper
Tolerance:	+ 10.00	- 10.00	%

Layer Type and Layer Number	Layer & Copper Description	Dielectric Discription Cu Area %	Via Structure
Soldermask			
Top 1	Primary Side Traces	100%	
Prepreg	EM-37B(5)	3.05mils (1080x1) 64%	
Pln 2		75%	
Prepreg	EM-37B(5)	3.05mils (1080x1) 64%	
Sig 3		45%	
Prepreg	EM-37B(5)	3.05mils (1080x1) 64%	
Sig 4		45%	
Prepreg	EM-37B(5)	3.05mils (1080x1) 64%	
Pln 5	Buried via plated	75%	
Core	EM-370(5)	3mils H/H (1080x1)	
Pln 6	Buried via plated	75%	
Prepreg	EM-37B(5)	3.05mils (1080x1) 64%	
Sig 7		45%	
Prepreg	EM-37B(5)	3.05mils (1080x1) 64%	
Sig 8		45%	
Prepreg	EM-37B(5)	3.05mils (1080x1) 64%	
Pln 9		75%	
Prepreg	EM-37B(5)	3.05mils (1080x1) 64%	
Bot 10	Secondary Side Traces	100%	
Soldermask			



CF3 for IoT – Partnership with Sierra





Sierra Wireless
Innovation Summit
2016

Discover, discuss and test tomorrow's IoT technologies and network with one of the most active IoT business and developer communities.

summit.sierrawireless.com